

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

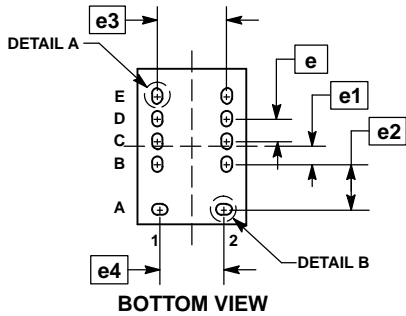
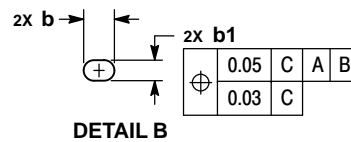
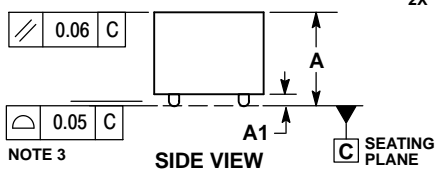
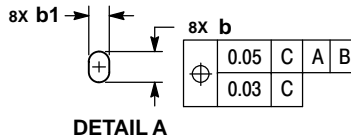
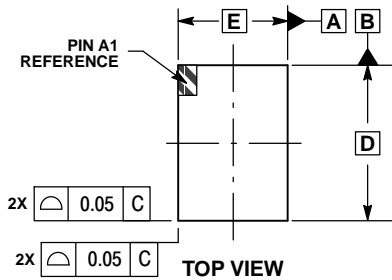
ON Semiconductor®



SCALE 4:1

WLCSP10, 1.03x0.72
CASE 567KD
ISSUE A

DATE 02 DEC 2014

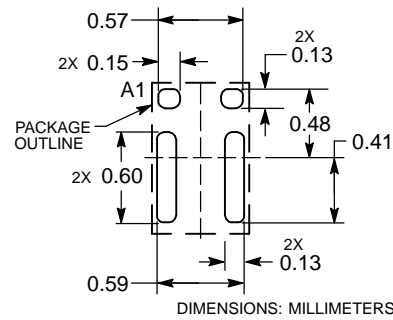


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.590	0.639
A1	0.069	0.093
b	0.079	0.129
b1	0.044	0.094
D	1.029 BSC	
E	0.722 BSC	
e	0.150 BSC	
e1	0.114 BSC	
e2	0.300 BSC	
e3	0.460 BSC	
e4	0.425 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP10, 1.03X0.72	PAGE 1 OF 2

